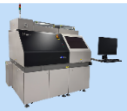
Multilayer Fan-out Packaging

Purpose	With a combination innovative optical design plus advanced inspection algorithm, STI offers various inspection & handling solutions to address stringent wafer level fan-out packaging requirements.
Technology	1. **On-the-Fly Dual Image Capture** – Captures two images using two independent illuminations. Enables capturing challenging multilayer features like RDL, Kerf, Overlay, Land Pads, Bumps and Top surface simultaneously without compromising throughput and inspection resolution. 2. **Dicing Defect Metrology** – Field proven inspection algorithm to inspect Edge & Corner Defects, Active Die, Saw Street Quality, Die Alignment on Stretched wafer, Die Edge Micro Crack Inspection, Die Shift Inspection and Overlay. 3. **3D LPS** – 3D metrology for high density micro bumps, Cu pillars, and RDL. 4. **OTF Triangulation 3D** – Designed for high-volume, high-speed 3D Metrology solutions for Post Dicing, Assembly & Post Test requirements.

STI Products	On-The-Fly Dual Image Capture	Dicing Defect Metrology	3D LPS	OTF Triangulation 3D
 **iFocus – Wafer 2D & 3D Scan**	✓	✓	✓	
 **Hexa – Tray 2D & 3D Scan**				✓
 **tSort – WLP Scan & Sort**		✓		
 **tScan – 2D & 3D High Speed Scan-Pack**				✓